PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tsutomu HARADA	10/23/2008
Yoshihiko DEOKA	10/23/2008
Hisato HIRASAKA	10/23/2008
Toshihiko HIROSE	10/23/2008
Toshiyuki HIROSE	10/23/2008
Osamu NAKAMURA	10/23/2008
Akira ITOU	10/23/2008

RECEIVING PARTY DATA

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Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12270004

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Tamika R. Gaston

Total Attachments: 3
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S08P1974US00

Docket Number: ____________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in RECORDING/REPRODUCING APPARATUS AND RECORDING/REPRODUCING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ____________________, Filing Date: ____________________.

This assignment executed on the dates indicated below.

Tsutomu HARADA — October 23, 2008
Name of first or sole inventor — Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of first or sole inventor

Tsutomu Harada — October 23, 2008
Signature of first or sole inventor — Date of this assignment

Yoshihiko DEOKA | October 23, 2008
Name of second inventor | Execution date of U.S. Patent Application

Tokyo, Japan
Residence of second inventor

Yoshihiko Deoka | October 23, 2008
Signature of second inventor | Date of this assignment

Hisato HIRASAKA | October 23, 2008
Name of third inventor | Execution date of U.S. Patent Application

Tokyo, Japan
Residence of third inventor

Hisato Hirasaka | October 23, 2008
Signature of third inventor | Date of this assignment

Toshihiko HIROSE | October 23, 2008
Name of fourth inventor | Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of fourth inventor

Toshihiko Hirose | October 23 2008
Signature of fourth inventor | Date of this assignment

Toshiyuki HIROSE | October 23, 2008
Name of fifth inventor | Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of fifth inventor

Toshiyuki Hirose | October 23, 2008
Signature of fifth inventor | Date of this assignment

Osamu NAKAMURA	October 23, 2008
Name of sixth inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of sixth inventor	
Osamu Nakamura	October 23, 2008
Signature of sixth inventor	Date of this assignment

Akira ITOU	October 23, 2008
Name of seventh inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of seventh inventor	
Akira Itou	October 23, 2008
Signature of seventh inventor	Date of this assignment

Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment

Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment